



# HSL278

## Silicon Schottky Barrier Diode for Detector

REJ03G0606-0100  
(Previous: ADE-208-1564)  
Rev.1.00  
Apr 20, 2005

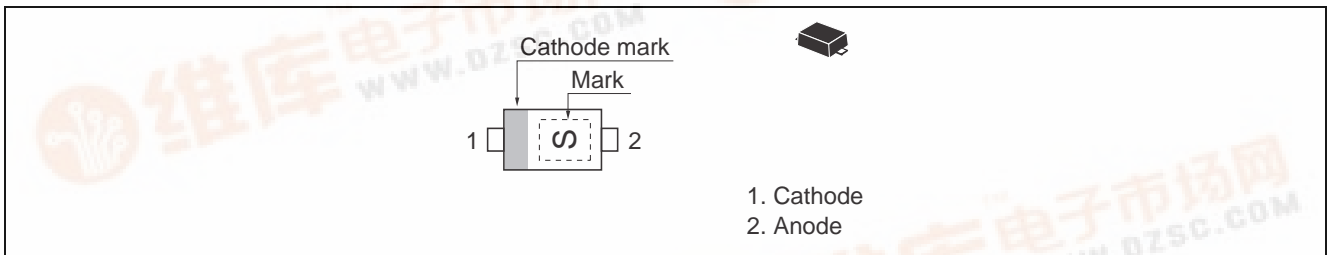
### Features

- Low forward voltage, Low capacitance.
- Extremely small Flat Lead Package (EFP) is suitable for surface mount design.

### Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HSL278	S	EFP	PXSF0002ZA-A (EFP)

### Pin Arrangement



## Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Repetitive peak reverse voltage	$V_{RRM}$	30	V
Reverse voltage	$V_R$	30	V
Average rectified current	$I_O$	30	mA
Non-Repetitive peak forward surge current	$I_{FSM}^*$	200	mA
Peak forward current	$I_{FM}$	150	mA
Junction temperature	$T_J$	125	°C
Storage temperature	$T_{stg}$	-55 to +125	°C

Note: 10 ms sine wave 1 pulse

## Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	$V_{F1}$	—	—	0.30	V	$I_F = 1 \text{ mA}$
	$V_{F2}$	—	—	0.95		$I_F = 30 \text{ mA}$
Reverse current	$I_R$	—	—	700	nA	$V_R = 10 \text{ V}$
Capacitance	C	—	—	1.5	pF	$V_R = 1 \text{ V}, f = 1 \text{ MHz}$
ESD-Capability *1	—	100	—	—	V	C = 200 pF, $R_L = 0 \Omega$ , Both forward and reverse direction 1 pulse.

Notes: 1. Failure criterion ;  $I_R \geq 1.4 \mu\text{A}$  at  $V_R = 10 \text{ V}$ 

2. Please do not use the soldering iron due to avoid high stress to the EFP package.

3. The material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

### Main Characteristic

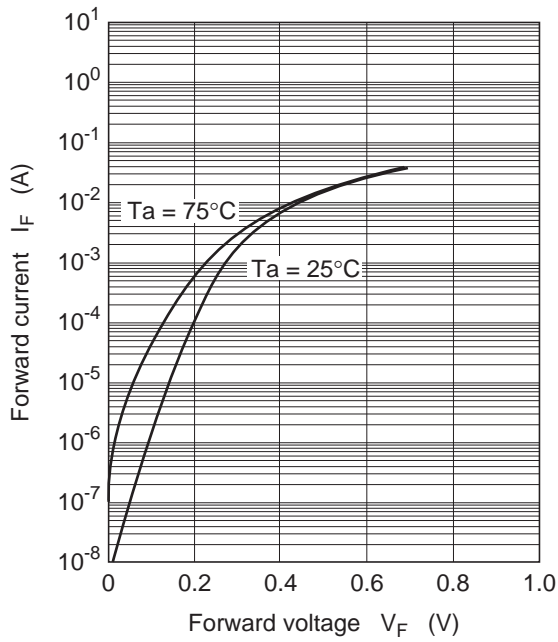


Fig.1 Forward current vs. Forward voltage

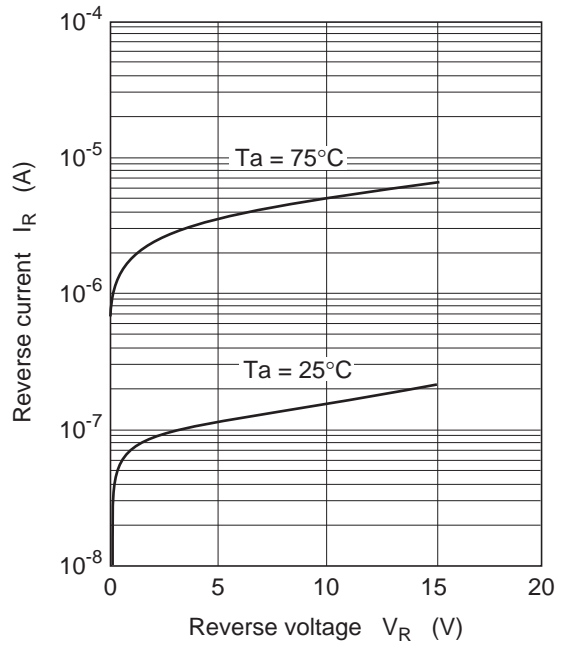


Fig.2 Reverse current vs. Reverse voltage

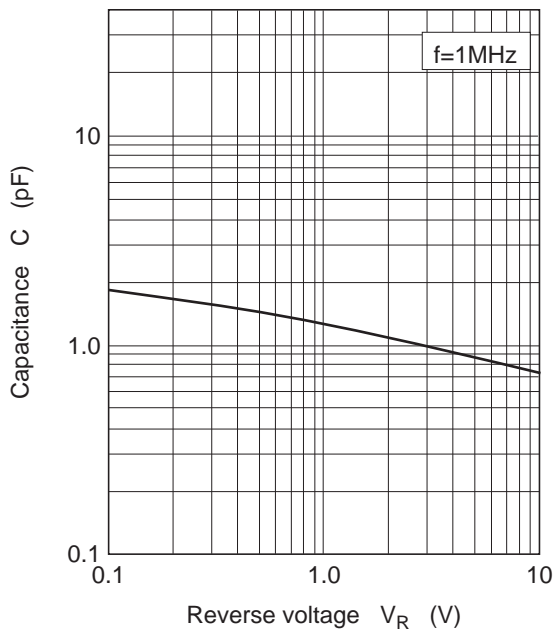
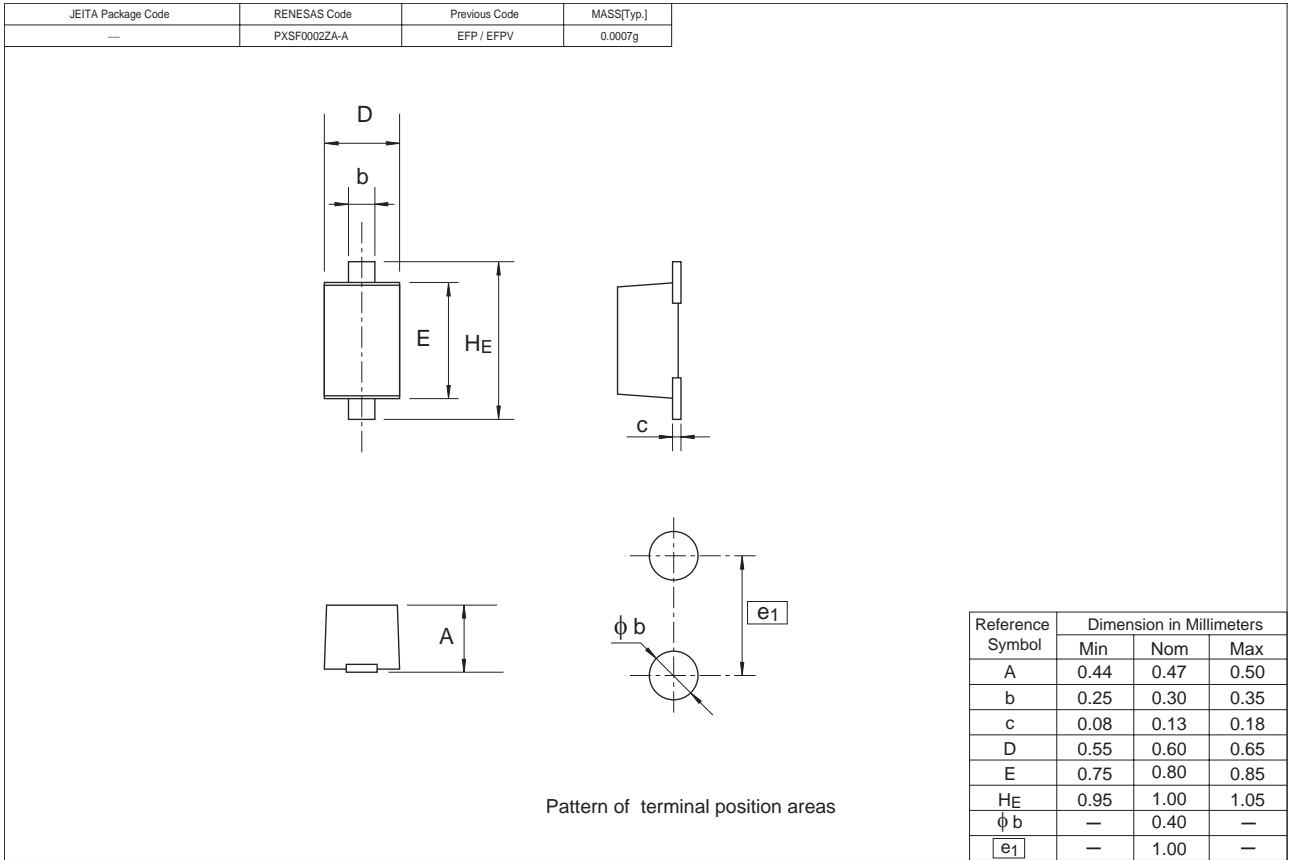


Fig.3 Capacitance vs. Reverse voltage

Package Dimensions



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